

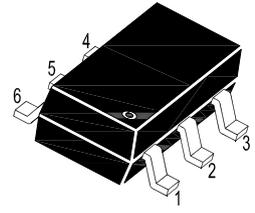
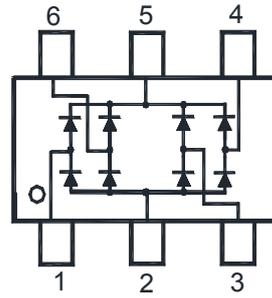
MMBD208D

Low Capacitance Diode Array

for ESD Protection

Features

- Low Capacitance
- Single Package Integration Design
- Ensures Data Line Speed and Integrity
- Fewer Components and Less Board Space



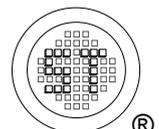
1. I/O 2. V_N 3. I/O
 4. I/O 5. V_P 6. I/O
 Marking Code : 20
 SOT-26 Plastic package

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	70	V
ESD Voltage (HBM)	V_{ESD}	15 8	KV
Non-Repetitive Peak Forward Surge Current	I_{FSM}	6 2 1	A
Operating Junction and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150	$^\circ\text{C}$

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Stand-Off Voltage	V_{RWM}	-	70	V
Reverse Breakdown Voltage at $I_{BR} = 50 \mu\text{A}$	$V_{(BR)R}$	85	-	V
Reverse Current at $V_R = 70\text{V}$	I_R	-	1	μA
Junction Capacitance at $V_R = 0\text{V}$, $f = 1\text{MHz}$, I/O to V_P at $V_R = 0\text{V}$, $f = 1\text{MHz}$, Between I/O lines	C_j	-	1 0.9	pF



MMBD208D

Electrical characteristic curves

Fig 1. Reverse Characteristic Curve

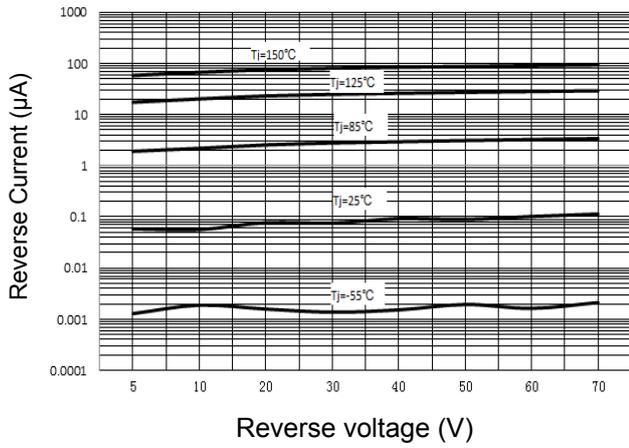


Fig 2. Forward Characteristic Curve

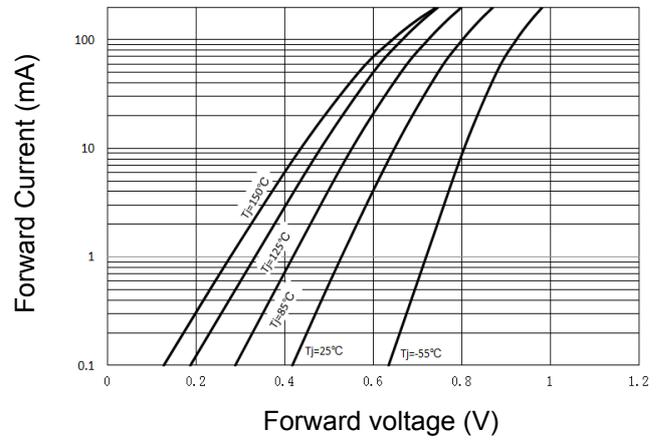
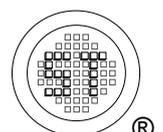
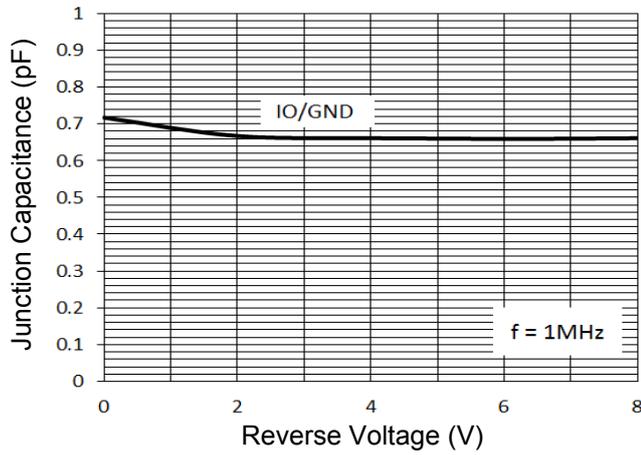


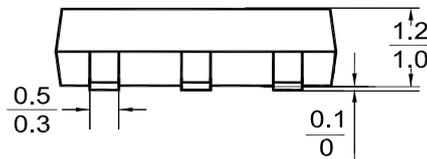
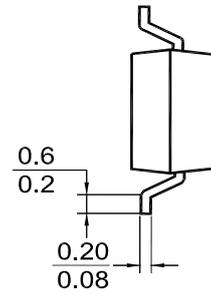
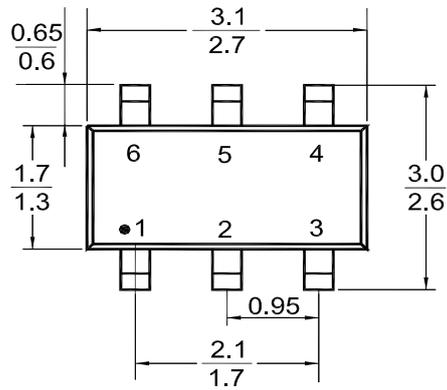
Fig 3. Junction Capacitance



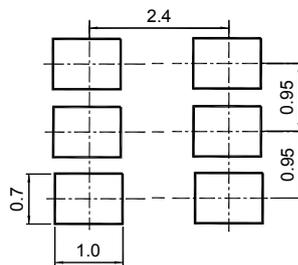
MMBD208D

Package Outline Dimensions (Units: mm)

SOT-26



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-26	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" 20" = Part No.
 "YM" = Date Code Marking
 "Y" = Year
 "M" = Month
 Font type: Arial

